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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **OZAKI, Takashi, et al.**

Attention: Applications Division

Serial Number: **10/528,137**

Group Art Unit: **1763**

Filed: **December 12, 2005**

P.T.O. Confirmation No.: **2307**

For: **SUBSTRATE PROCESSING APPARATUS AND METHOD FOR
MANUFACTURING A SEMICONDUCTOR DEVICE**

REQUEST FOR CORRECTED FILING RECEIPT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Date: April 18, 2006

Sir:

Please supply the undersigned attorney with a corrected filing receipt for the above-identified application. The undersigned also respectfully requests that the Patent and Trademark Office records be amended to reflect the correction.

In reviewing the official Filing Receipt, we noted an error in that the **title is incorrect and should read as - -SUBSTRATE PROCESSING APPARATUS AND METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE- -**. A copy of the **Declaration** is enclosed which indicates the correct information. We are enclosing a copy of the filing receipt with the corrections highlighted.

In the event that any fees are required in connection with this paper, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, KRATZ, QUINTOS,
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WLB/bjb

Atty. Docket No. **050161**
Suite 1000
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PATENT TRADEMARK OFFICE

Enclosures: Official Filing Receipt and Declaration



UNITED STATES PATENT AND TRADEMARK OFFICE

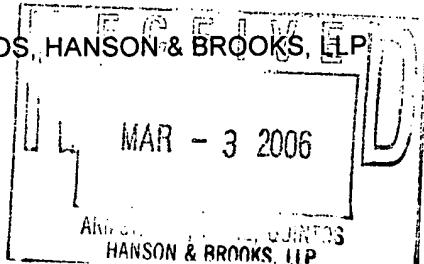


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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/528,137	12/12/2005	1763	1630	050161	9	20	6

CONFIRMATION NO. 2307

23850
ARMSTRONG, KRATZ, QUINTOS, HANSON & BROOKS, LLP
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FILING RECEIPT



OC00000001814158

Date Mailed: 02/28/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Power of Attorney: The patent practitioners associated with Customer Number 23850.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP04/01996 02/20/2004

Foreign Applications

JAPAN 2003-44049 02/21/2003
JAPAN 2003-44904 02/21/2003
JAPAN 2003-87966 03/27/2003
JAPAN 2003-87884 03/27/2003

Projected Publication Date: 06/08/2006

Non-Publication Request: No

See
3/6/06

Early Publication Request: No

*Substrate processing apparatus and method for manufacturing a
semiconductor device --
Substrate-processing apparatus and method of producing a semiconductor device*

Preliminary Class

118

PROTECTING YOUR INVENTION OUTSIDE THE UNITED STATES

Since the rights granted by a U.S. patent extend only throughout the territory of the United States and have no effect in a foreign country, an inventor who wishes patent protection in another country must apply for a patent in a specific country or in regional patent offices. Applicants may wish to consider the filing of an international application under the Patent Cooperation Treaty (PCT). An international (PCT) application generally has the same effect as a regular national patent application in each PCT-member country. The PCT process **simplifies** the filing of patent applications on the same invention in member countries, but **does not result** in a grant of "an international patent" and does not eliminate the need of applicants to file additional documents and fees in countries where patent protection is desired.

Almost every country has its own patent law, and a person desiring a patent in a particular country must make an application for patent in that country in accordance with its particular laws. Since the laws of many countries differ in various respects from the patent law of the United States, applicants are advised to seek guidance from specific foreign countries to ensure that patent rights are not lost prematurely.

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Applicants may wish to consult the USPTO booklet, "General Information Concerning Patents" (specifically, the section entitled "Treaties and Foreign Patents") for more information on timeframes and deadlines for filing foreign patent applications. The guide is available either by contacting the USPTO Contact Center at 800-786-9199, or it can be viewed on the USPTO website at <http://www.uspto.gov/web/offices/pac/doc/general/index.html>.

For information on preventing theft of your intellectual property (patents, trademarks and copyrights), you may wish to consult the U.S. Government website, <http://www.stopfakes.gov>. Part of a Department of Commerce initiative, this website includes self-help "toolkits" giving innovators guidance on how to protect intellectual property in specific countries such as China, Korea and Mexico. For questions regarding patent enforcement issues, applicants may call the U.S. Government hotline at 1-866-999-HALT (1-866-999-4158).

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DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SUBSTRATE PROCESSING APPARATUS AND METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

the specification of which is attached hereto unless the following is checked

was filed on _____ as United States Application Number or PCT International

Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

(List prior foreign applications. See note A)

Priority Claimed			
<u>2003-44049</u> (Number)	<u>Japan</u> (Country)	<u>21/2/2003</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<u>2003-44904</u> (Number)	<u>Japan</u> (Country)	<u>21/2/2003</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<u>2003-87966</u> (Number)	<u>Japan</u> (Country)	<u>27/3/2003</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<u>2003-87884</u> (Number)	<u>Japan</u> (Country)	<u>27/3/2003</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No

(See note B)

See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List prior U.S. Applications)

<u>(Application Serial No.)</u>	<u>(Filing Date)</u>
<u>(Application Serial No.)</u>	<u>(Filing Date)</u>
<u>(Application Serial No.)</u>	<u>(Filing Date)</u>

Status

Patented Pending Abandoned

Patented Pending Abandoned

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